



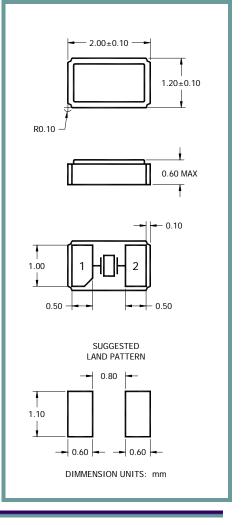
## **Product Features:**

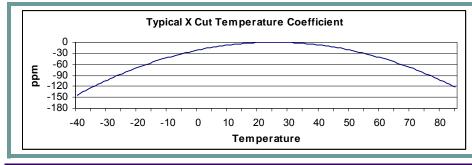
Low Cost SMD Package **RoHS** Compliant Compatible with Leadfree Processing Ultra Low Profile

## **Applications:**

**Real Time Clocks** Metering Industrial Control Time Reference

| Frequency                               | 32.768 KHz   |  |
|---|--|--|
| ESR (Equivalent Series Resistance)      | Less than 90 k $\Omega$  |  |
| Shunt Capacitance (C0)                  | 1.3 рҒ Тур.  |  |
| Motional Capacitance (CI)               | 6.5 fF Typ.  |  |
| Frequency Tolerance @ 25° C ±5°C        | ±20 ppm Standard   |  |
| Frequency Stability over<br>Temperature | Parabolic -0.034 ppm / $^\circ$ C² Typ. Turnover point +25° ±5°C See Graph Below |  |
| Crystal Cut                             | X-Cut  |  |
| Load Capacitance                        | 12.5 pF Standard   |  |
| Drive Level                             | 0.1 µW Тур., 0.5 µW Мах.   |  |
| Aging                                   | $\pm$ 5 ppm Max. / Year Standard   |  |
| Temperature                             |  |  |
| Operating                               | -40° C to +85° C Standard  |  |
| Storage                                 | -55° C to +125° C Standard   |  |





| Part Number Guide | •   | Sample Part Number:                              | : IL3T - HX5F12.               | 5 - 32.768 KHz    |                          |              |
|-------------------|---|--|--------------------------------|-------------------|--------------------------|--------------|
| Package           | Stability<br>(ppm) at Room<br>Temperature | Stability<br>(ppm) over Operating<br>Temperature | Operating<br>Temperature Range | ode<br>(overtone) | Load Capacitance<br>(pF) | Frequency    |
| IL3T -            | H = ±20 ppm                               | X = X Cut  | 5 = -40°C to +85°C             | F = Fundamental   | 12.5 pF Standard         | - 32.768 KHz |





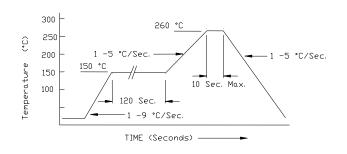


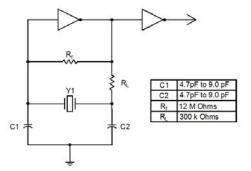
# 2 Pad Ceramic Base SMD Crystal, 2.0 mm x 1.2 mm



## **Pb Free Solder Reflow Profile:**

**Typical Circuit:** 



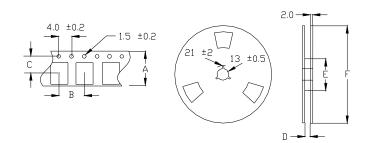


\*Units are backward compatible with 240C reflow processes

### **Package Information:**

MSL = 2Termination = e1 (Sn/Cu/Ag over Ni over Kovar base metal)

## **Tape and Reel Information:**



| Quantity per<br>Reel | 3000      |
|----------------------|-----------|
| Α                    | 8.0 ±0.2  |
| В                    | 4.0 ±0.1  |
| С                    | 3.5 ±0.05 |
| D                    | 9.0 ±0.3  |
| E                    | 60 / 80   |
| F                    | 180 / 250 |

## **Environmental Specifications**

| Thermal Shock                | MIL-STD-883, Method 1011, Condition A                       |
|------------------------------|---|
| Moisture Resistance          | MIL-STD-883, Method 1004                                    |
| Mechanical Shock             | MIL-STD-883, Method 2002, Condition B                       |
| Mechanical Vibration         | MIL-STD-883, Method 2007, Condition A                       |
| Resistance to Soldering Heat | J-STD-020C, Table 5-2 Pb-free devices (except 2 cycles max) |
| Hazardous Substance          | Pb-Free / RoHS / Green Compliant                            |
| Solderability                | JESD22-B102-D Method 2 (Preconditioning E)                  |
| Terminal Strength            | MIL-STD-883, Method 2004, Test Condition D                  |
| Gross Leak                   | MIL-STD-883, Method 1014, Condition C                       |
| Fine Leak                    | MIL-STD-883, Method 1014, Condition A2, R1=2x10-8 atm cc/s  |
| Solvent Resistance           | MIL-STD-202, Method 215                                     |

### Marking

Line 1: Frequency, Date Code

#### **PROPRIETARY AND CONFIDENTIAL**

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION, AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE NOR USED FOR MANUFACTURING PURPOSES WITHOUT WRITTEN PERMISSION FROM ILSI America.



